



## P-Channel Enhancement Mode MOSFET

### ➤ Features

VDS	VGS	RDSON Typ.	ID
-20V	±12V	20mR@-4V5	-7A
		25mR@-2V5	

### ➤ Description

This device is produced with high cell density DMOS trench technology, which is especially used to minimize on-state resistance. This device particularly suits low voltage applications such as portable equipment, power management and other battery powered circuits.

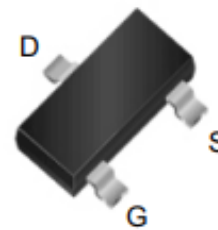
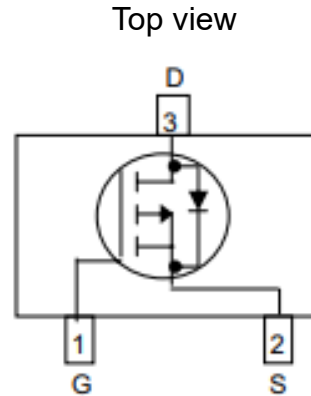
### ➤ Applications

- Load Switch
- Portable Devices
- DCDC conversion

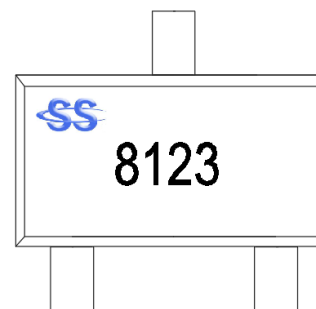
### ➤ Ordering Information

Device	Package	Shipping
SSC8123GS6A	SOT23-3L	3000/Reel

### ➤ Pin configuration



SOT23-3L



Marking



➤ **Absolute Maximum Ratings**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain-to-Source Voltage	-20	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 12$	V
$I_D$	Continuous Drain Current <sup>a</sup>	-7	A
$I_{DM}$	Pulsed Drain Current <sup>b</sup>	-21	A
$P_D$	Power Dissipation <sup>c</sup>	1.6	W
$T_J$	Operation junction temperature	-55 to 150	$^{\circ}\text{C}$
$T_{STG}$	Storage temperature range	-55 to 150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	78	$^{\circ}\text{C}/\text{W}$

Note:

- The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ . The value in any given application depends on the user is specific board design.
- Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}=150^{\circ}\text{C}$ .
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^{\circ}\text{C}$ , using steady state junction-to-ambient thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

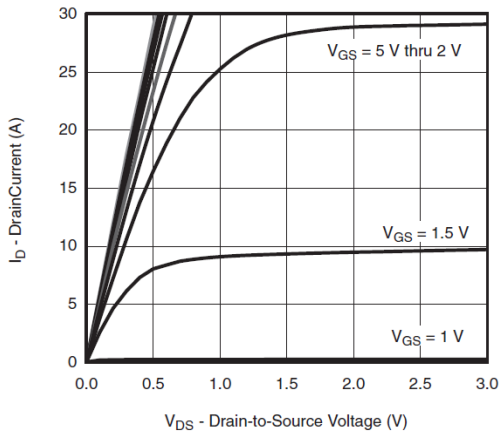


➤ **Electronics Characteristics**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

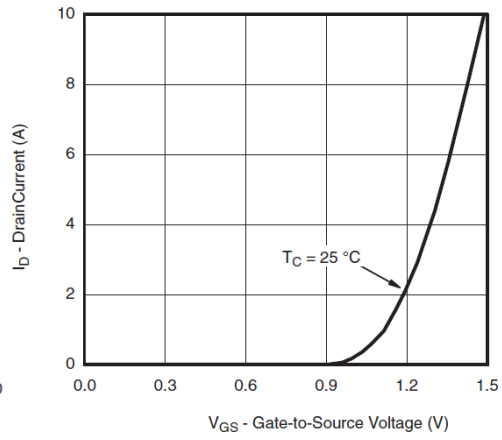
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.7	-0.9	V
$R_{DS(on)}$	Drain-Source On- Resistance	$V_{GS}=-4.5V, I_D=-5A$		20	26	mR
		$V_{GS}=-2.5V, I_D=-3A$		25	36	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-16V, V_{GS}=0V$			-1	$\mu A$
$I_{GSS}$	Gate-Source leak current	$V_{GS}=\pm 12V, V_{DS}=0V$			$\pm 100$	nA
$G_{FS}$	Transconductance	$V_{DS}=-5V, I_D=-5A$		10		S
$V_{SD}$	Forward Voltage	$V_{GS}=0V, I_S=-2A$		-0.78	-1.2	V
$C_{iss}$	Input Capacitance	$V_{DS}=-10V, V_{GS}=0V, f=1MHz$		1430		pF
$C_{oss}$	Output Capacitance			182		
$C_{rss}$	Reverse Capacitance			160		
$T_{D(ON)}$	Turn-on delay time	$V_{DS}=-10V,$ $V_{GEN}=-4.5V, R_L=1.43R$ $R_G=3R$		11		ns
$T_r$	Rise Time			18		
$T_{D(OFF)}$	Turn-off delay time			45		
$T_f$	Fall Time			23		
$Q_g$	Total Gate charge	$V_{GS}=-4.5V, V_{DS}=-10V$ $I_D=-7A$		15		nC
$Q_{gs}$	Gate Source charge			3		
$Q_{gd}$	Gate Drain charge			4		



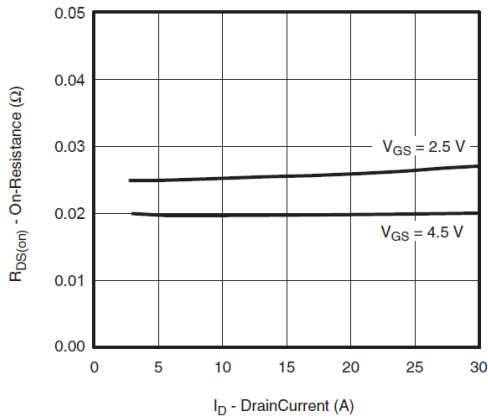
➤ **Typical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)



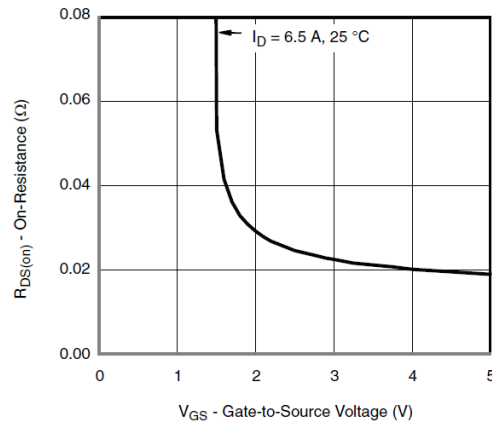
**Output Characteristics**



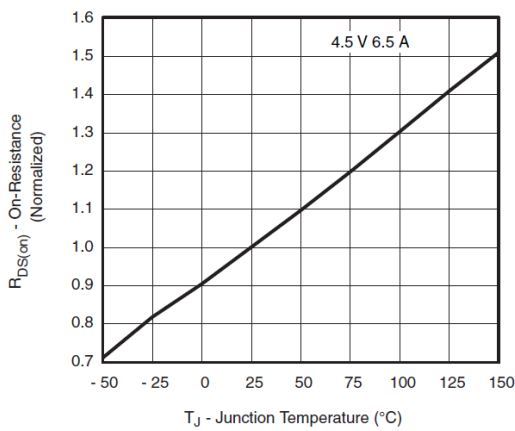
**Transfer Characteristics**



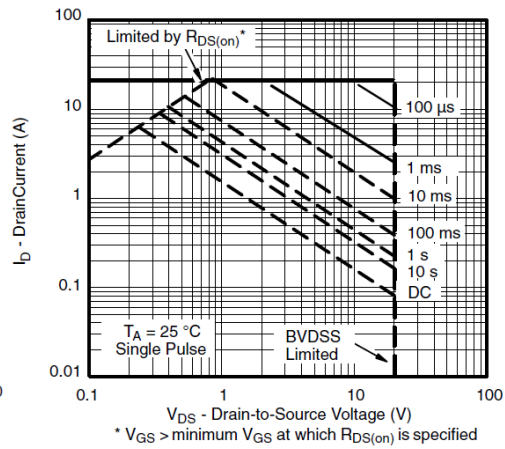
**On-Resistance vs. Drain Current and Gate Voltage**



**On-Resistance vs. Gate-to-Source Voltage**



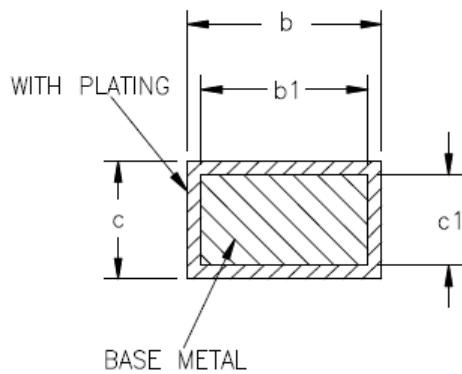
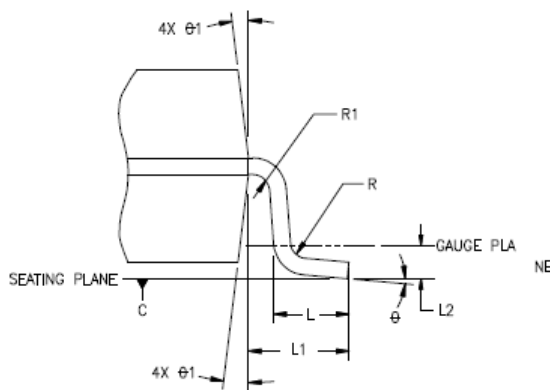
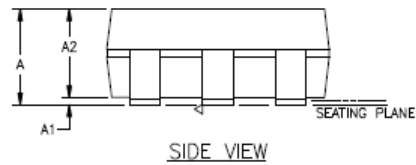
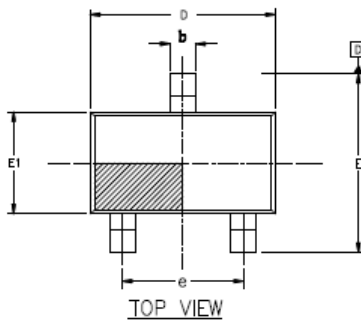
**On-Resistance vs. Junction Temperature**



**Safe Operating Area, Junction-to-Ambient**



➤ Package Information



SYMBOL	MIN	NOM	MAX
A	--	--	1.35
A1	0	--	0.15
A2	1.0	1.1	1.2
b	0.35	--	0.45
b1	0.32	--	0.38
c	0.14	--	0.20
c1	0.14	0.15	0.16
D	2.82	2.92	3.02
E	2.60	2.80	3.00
E1	1.526	1.626	1.726
e	1.8	1.9	2.0
L	0.35	0.45	0.6
L1	0.6REF		
L2	0.25REF		
R	0.1	--	--
R1	0.1	--	--
θ	0°	4°	8°
θ1	5°	10°	15°

**NOTES:**  
 1. ALL DIMENSIONS REFER TO JEDEC STANDARD MO-178  
 2. DIMENSION D DOES NOT INCLUDE MOLD FLASH  
 3. DIMENSION E1 DOES NOT INCLUDE MOLD FLASH  
 4. FLASH OR PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE.

SOT23-3L



**DISCLAIMER**

AFSEMI RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. AFSEMI DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENCE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

THE GRAPHS PROVIDED IN THIS DOCUMENT ARE STATISTICAL SUMMARIES BASED ON A LIMITED NUMBER OF SAMPLES AND ARE PROVIDED FOR INFORMATIONAL PURPOSE ONLY. THE PERFORMANCE CHARACTERISTICS LISTED IN THEM ARE NOT TESTED OR GUARANTEED. IN SOME GRAPHS, THE DATA PRESENTED MAY BE OUTSIDE THE SPECIFIED OPERATING RANGE (E.G. OUTSIDE SPECIFIED POWER SUPPLY RANGE) AND THEREFORE OUTSIDE THE WARRANTED RANGE.